

AP163

Injection Molding Grade

Description

- Very Low Surface Resistivity

Applications

- COG(Chip on Glass) Tray for Semiconductor

Properties	Method	Unit	AP163
Physical			
Specific Gravity , 23°C	ASTM D792		1.06
Mold Shrinkage , 23°C, 3.2mm , 23°C	ASTM D955	%	0.4 ~ 0.7
Melt Flow Rate , 220°C, 10kg	ASTM D1238	g/10min	30
Mechanical			
Tensile Strength at Yield , 23°C, 50mm/min, 3.2mm	ASTM D638	MPa	41
Tensile Elongation at Yield , 23°C, 50mm/min, 3.2mm	ASTM D638	%, (Min)	5
Tensile Elongation at Break , 23°C, 50mm/min, 3.2mm	ASTM D638	%, (Min)	10
Tensile Modulus , 23°C, 50mm/min, 3.2mm	ASTM D638	MPa	1750
Flexural Strength , 23°C, 15mm/min, 3.2mm	ASTM D790	MPa	67
Flexural Modulus , 23°C, 15mm/min, 3.2mm	ASTM D790	MPa	2050
Izod Impact Strength , Notched, 3.2mm, 23°C	ASTM D256	J/m	440
Izod Impact Strength , Notched, 3.2mm, -30°C	ASTM D256	J/m	180
Izod Impact Strength , Notched, 6.4mm, 23°C	ASTM D256	J/m	420
Izod Impact Strength , Notched, 6.4mm, -30°C	ASTM D256	J/m	180
Rockwell Hardness , R-Scale	ASTM D785		98
Thermal			
HDT , Edgewise, 1.82MPa, 6.4mm, Unannealed	ASTM D648	°C	83
VICAT , 50N, 50°C/h	ASTM D1525	°C	91
RTI Electrical	UL 746B	°C	60
RTI Mechanical with Impact	UL 746B	°C	60
RTI Mechanical without Impact	UL 746B	°C	60
Flammability, 1.5mm	UL 94		HB
Flammability, 3.0mm	UL 94		HB

Note

Typical values can be used only for the purpose of selecting material, and there can be variation within normal tolerances for various colors. Values given should not be interpreted as specification and not be used for designing part or tool. All properties, except melt flow rate are measured by injection molded specimens after 48 hours storage at 23°C, 50% relative humidity.

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Processing Guide (Injection Molding)

Processing Parameters	Unit	Value
Drying Temperature	°C	80 ~ 80
Drying Time	hrs	2 ~ 4
Moisture Content	%	0.01 ~
Melt Temperature	°C	210 ~ 240
Nozzle Temperature	°C	200 ~ 250
Mold Temperature	°C	40 ~ 70
Back Pressure, Hydraulic Type	kg/cm ²	5 ~ 15
Screw Speed	rpm	30 ~ 60

Note

Back Pressure & Measuring Speed are only mentioned as general guidelines.

These may not apply or need adjustment in specific situations such as low shot sizes, thin wall molding and gas-assist molding.

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